

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 05/09/2022

Details for "OPA358AIDCKR"

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
OPA358AIDCKR	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DCK   6	2x1.3x0.9	7.1

\*Total Device Mass  
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Precious Metals	Gold	7440-57-5	0.028261	100	1000000	0.396072	3961
Sub-Total			0.028261	100	1000000	0.396072	3961
<b>Die Attach Adhesive</b>							
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.014892	30	300000	0.208708	2087
Other Inorganic Materials	Silica	7631-86-9	0.002234	4.500403	45004	0.031309	313
Other Organic Materials	Chlorine	7782-50-5	0.000017	0.034247	342	0.000238	2
Thermoplastics	Epoxy	85954-11-6	0.032497	65.465351	654654	0.455439	4554
Sub-Total			0.04964	100	1000000	0.695695	6957
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	2.923125	97.4375	974375	40.967019	409670
Copper and Its Alloys	Iron	7439-89-6	0.0705	2.35	23500	0.988044	9880
Copper and Its Alloys	Phosphorus	7723-14-0	0.002475	0.0825	825	0.034687	347
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00015	0.005	50	0.002102	21
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.00375	0.125	1250	0.052556	526
Sub-Total			3	100	1000000	42.044406	420444
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.09512	95.12	951200	1.333088	13331
Precious Metals	Gold	7440-57-5	0.00078	0.78	7800	0.010932	109
Precious Metals	Palladium	7440-05-3	0.0041	4.1	41000	0.057461	575
Sub-Total			0.1	100	1000000	1.40148	14015
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	3.408215	93.250006	932500	47.765459	477655
Other Plastics and Rubber	Carbon Black	1333-86-4	0.009137	0.249992	2500	0.128053	1281
Thermoplastics	Epoxy	85954-11-6	0.23757	6.500002	65000	3.329497	33295
Sub-Total			3.654922	100	1000000	51.223009	512230
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	0.30249	100	1000000	4.239338	42393
Sub-Total			0.30249	100	1000000	4.239338	42393
<b>Total</b>			7.135313			100	1000000

**Important Note**  
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.  
[See Glossary of Terms for more details.](#)

**Important Part Information**  
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**  
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former IIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**  
 TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."  
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.